Nb₃Sn coating on Cu via CVD

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Collaborators and work presented on behalf of colleagues at Ultramet, Jefferson Lab, and FSU

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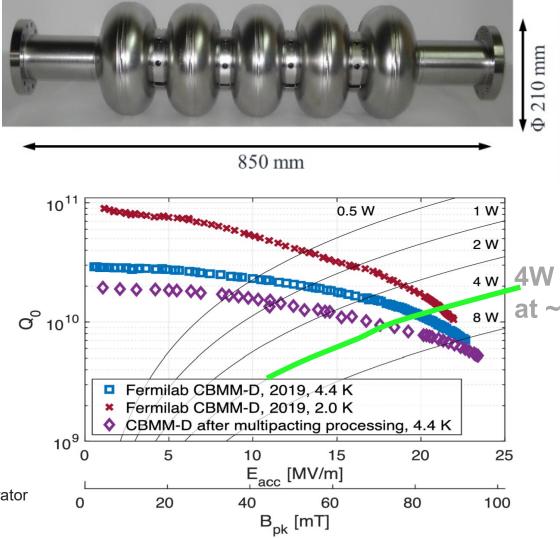


Beyond SRF Nb- Alternative materials:

Focus on Nb₃Sn

Property	Nb	Nb ₃ Sn ^a
T_c [K]	9.2	18
$\mu_0 H_{c1}(0)$ [T]	0.17	0.038
$\mu_0 H_c(0)$ [T]	0.2	0.52
$\mu_0 H_{c2}(0)$ [T]	0.4	30
$\xi_{GL}(0) [\text{nm}]^{\text{b}}$	29	3.3
$\lambda_{eff}(0) [\text{nm}]^{\text{c}}$	41	135

Posen, S., Lee, J., Seidman, D. N., Romanenko, A., Tennis, B., Melnychuk, O. S., & Sergatskov, D. A. (2021). Advances in Nb₃Sn superconducting radiofrequency cavities towards first practical accelerator applications. Superconductor Science and Technology, 34(2), 025007.



















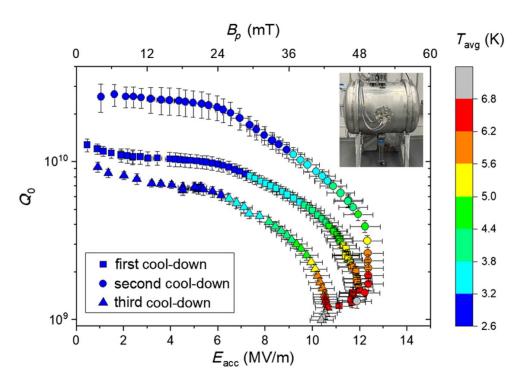


^a Approaching stoichiometry.

^b From $\sqrt{\phi_0/(2\pi\mu_0 H_{c2}(0))}$ [8].

^c From $\sqrt{\phi_0 \mu_0 H_{c2}(0)/(4\pi H_c^2)}$ [8].

Cryocooled Nb₃Sn on Nb successfully tested in Jefferson Lab- 1MW, 1MeV compact electron accelerator possible.

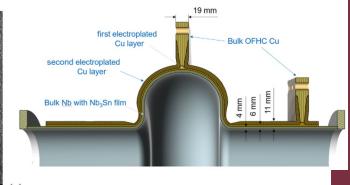


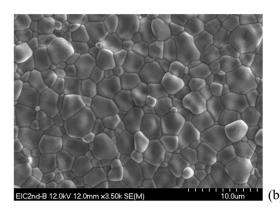
Development of a prototype superconducting radio-frequency cavity for conduction-cooled accelerators

G. Ciovati[©], ^{1,2,*} J. Anderson, ³ S. Balachandran, ¹ G. Cheng[©], ¹ B. Coriton, ^{3,†} E. Daly, ¹ P. Dhakal[®], A. Gurevich, F. Hannon, K. Harding[®], L. Holland, F. Marhauser[®], K. McLaughlin[®], D. Packard[®], T. Powers, U. Pudasaini[®], J. Rathke, R. Rimmer, L. T. Schultheiss[©], H. Vennekate[©], and D. Vollmer³

¹Thomas Jefferson National Accelerator Facility, Newport News, Virginia 23606, USA ²Center for Accelerator Science, Department of Physics, Old Dominion University, Norfolk, Virginia 23529, USA ³General Atomics, San Diego, California 92121, USA ⁴TECHSOURCE, Inc., Los Alamos, New Mexico 87544, USA ⁵TJS Technologies LLC, Commack, New York 11725, USA

EIC2nd-B 12.0kV 12.0mm x350 SE(M)





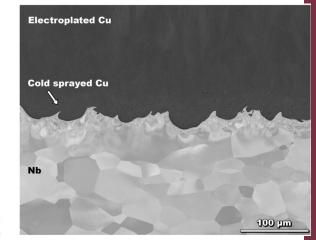


FIG. 9. (a) Low ($\times 350$) and (b) High magnification ($\times 3.5$ k) SEM images of the Nb₃Sn film on a Nb witness sample after the second coating.

10 MeV, 1 MW system in the works!





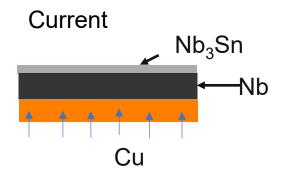


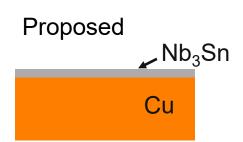


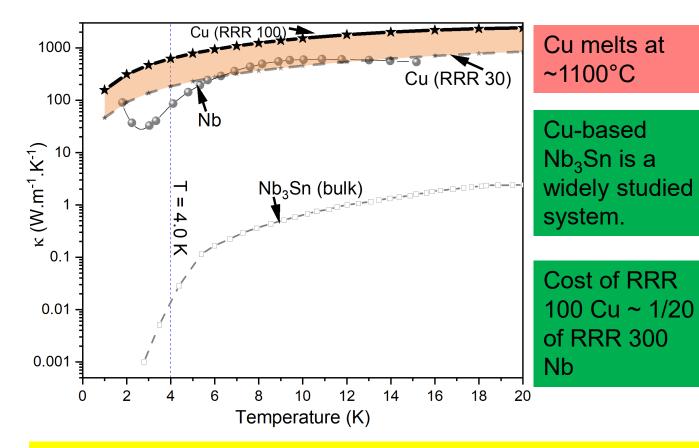




Nb₃Sn on Cu for SRF applications







~ 5 times improvement in thermal conductivity at 4K with Cu

















CVD Nb₃Sn by Nb and Sn chloride reactions

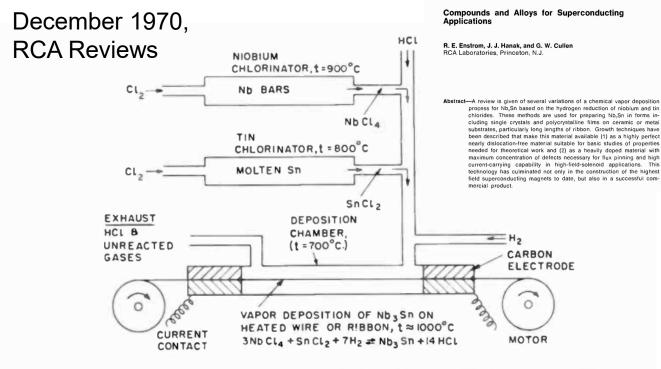
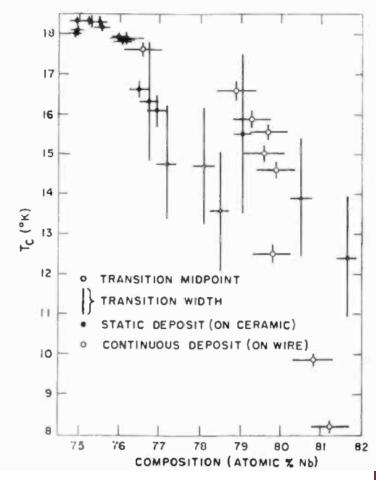


Fig. 2-Apparatus for continuous vapor deposition of Nb₃Sn on metallic ribbon and wire.

Deposition temperature is 700°C

Ribbon or wire heated to ~1000 °C



Nb: Sn vapor ratio control is important









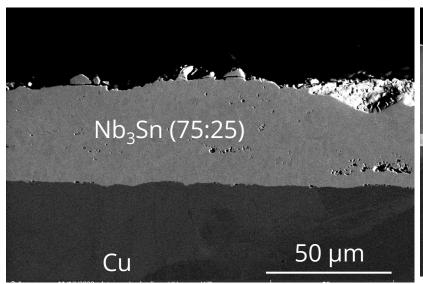


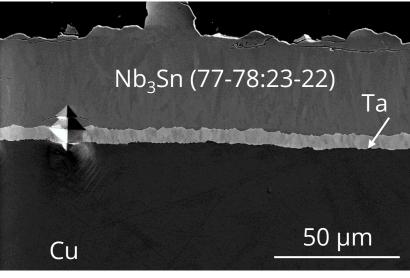


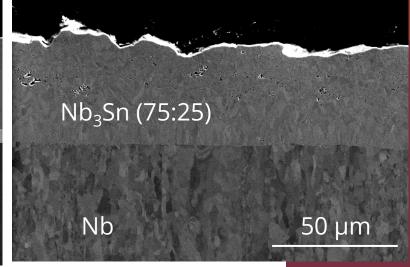




Ultramet, Inc deposited Nb₃Sn on Cu cavities at temperatures of 750°C - 900°C







Precursors are largely proprietary. Process details are unknown.







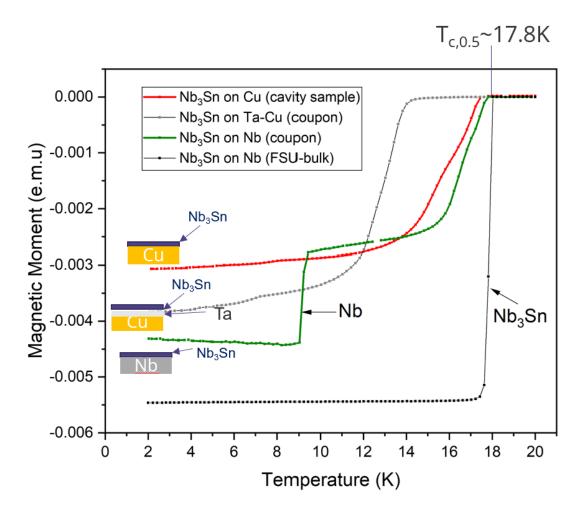




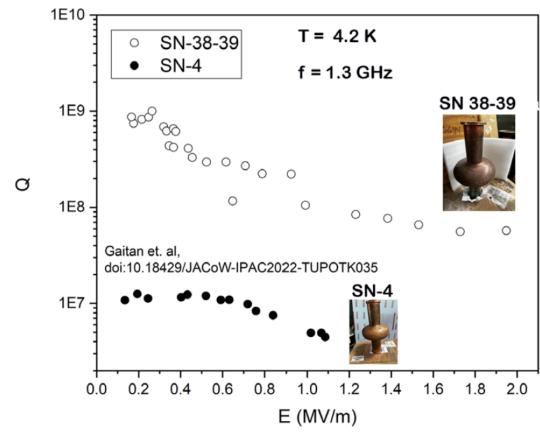




High T_c, Nb₃Sn is possible in the temperature range of 750- 900°C.



Cavity performance needs to improvement









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Issues beyond obtaining high-quality CVD Nb₃Sn need to be addressed for success in SRF applications.

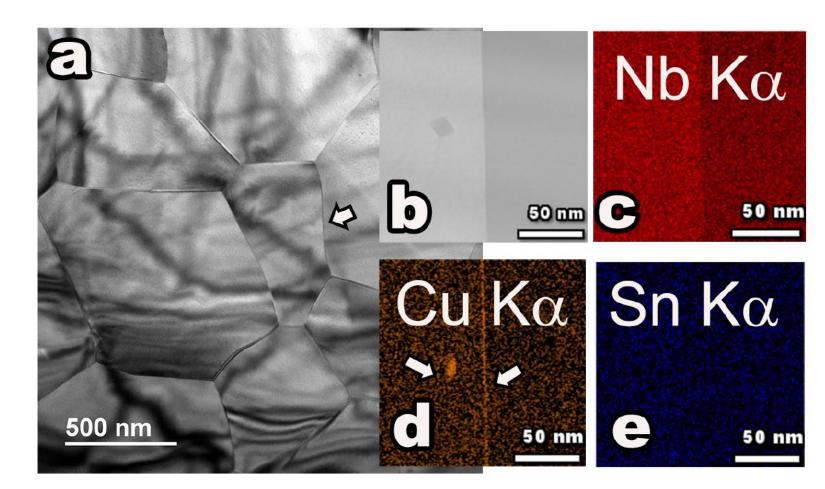








Cu in Nb₃Sn {grain boundaries}



Degradation of performance due to Cu in GB's.

Cu Diffusion barriers are important





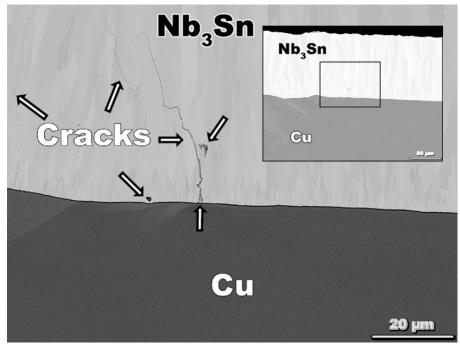


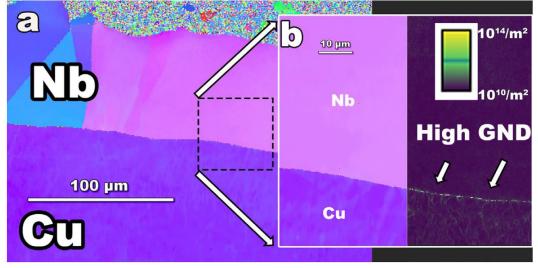






Thermal strains: Coefficient of thermal expansion.





Thermal expansion mismatch:

• Cu: 17 x 10⁻⁶/°C

• $Nb_3Sn: 7.6 \times 10^{-6}$ °C

• Nb/ Ta: ~8 x 10⁻⁶/°C







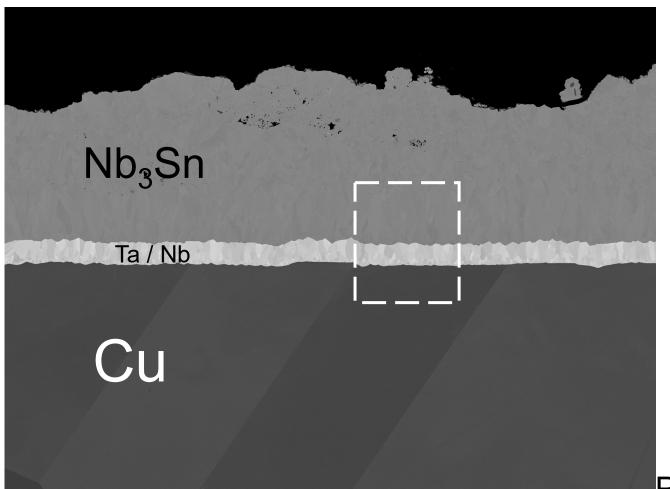


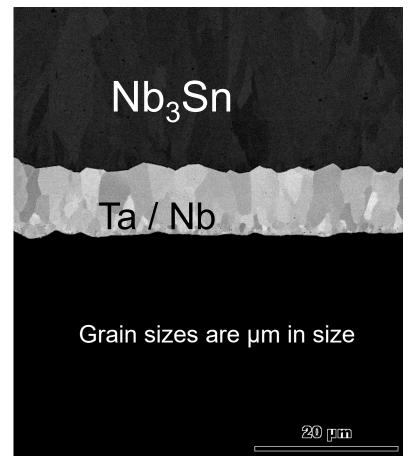






Surface roughness: Substrate + growth





Polishing processes for Nb₃Sn











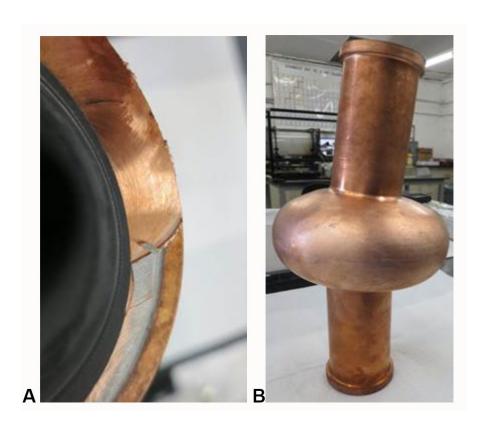


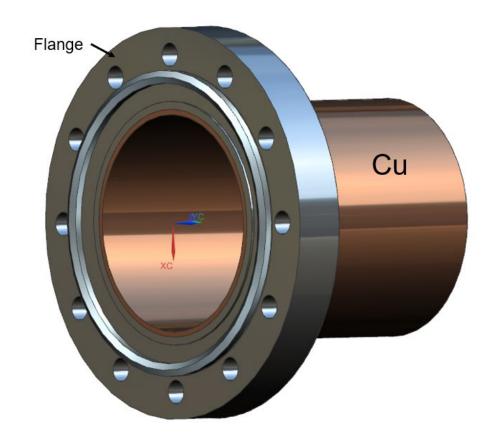






Structural stability of Cu structures after heat treatments















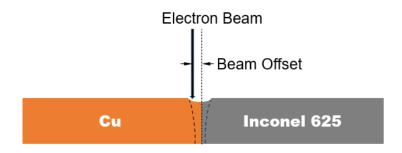


RD&D at Jefferson Lab to weld Inconel 625 to Cu

Inconel 625- 3.1mm sheet and 1 in. plate

Element	Weight percent	
Chromium	22.0	
Molybdenum	9	
Niobium + Tantalum	1.2	
Iron	1.8	
Aluminum	0.3	
Titanium	0.26	
Silicon	0.16	
Manganese	0.3	
Carbon	0.04	
Sulphur + Phosphorus	<0.005	
Nickel	Bal.	

Cu- C10100, off the shelf- 3.1 mm sheet



Welding parameters for 3mm thick sheets of Cu and Inconel 625. Beam current = 50 mA, beam Voltage = 50 kV, and oscillation diameter of 2mm, 10 kHz.

Sample ID	Weld speed (mm/s)	Beam Offset (mm)	Energy per unit length (W/mm)	Beam Offset
O1-C	6.8	0.4	328	1
O2-C	6.8	0.6	328	
O3-C	6.8	0.9	328	
O4-C	6.8	1.1	328	In Cu
V1-C	7.6	1.0	328	
V2-C	6.8	1.0	369	
V3-C	5.9	1.0	422	
V4-C	5.1	1.0	492	In A-
O7-I	7.2	0.4	328	625
O8-I	7.2	1.0	328	025

















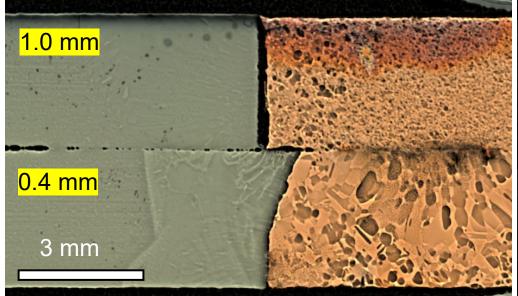


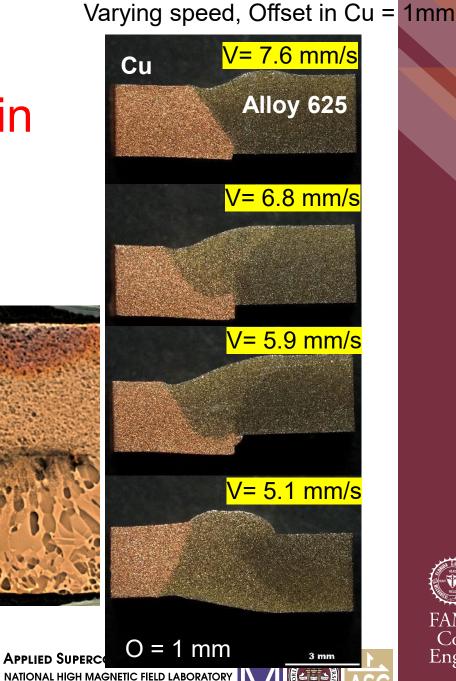


Offset in Cu, v = 6.8 mm/sAlloy 625 Cu 0.4 mm 0.6 mm 0.9 mm .1 mm Office of ENERGY Science

EB welds Cu to Inconel 625. Offset in Cu NOT in Inconel

Offset in Inconel 625, v = 6.8 mm/s



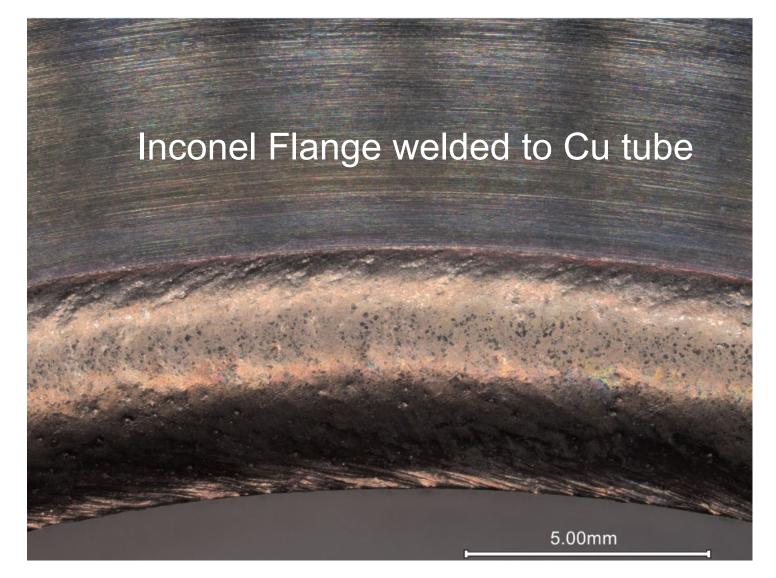


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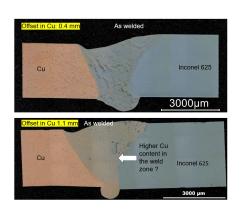


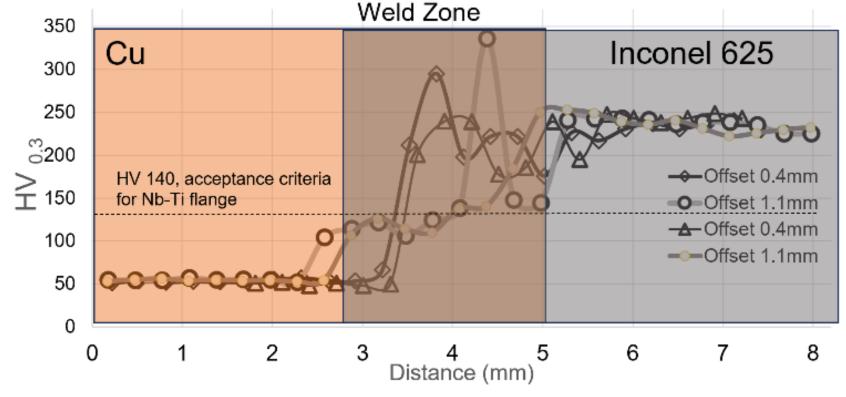






Cu- Inconel welds maintain high strength after welding.









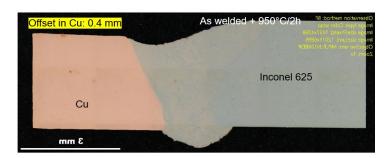




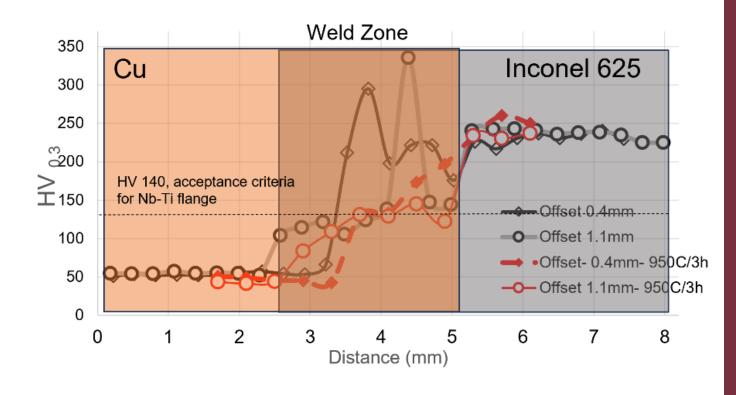




And continue to maintain higher strength after heating to 950°C for 3 hours.











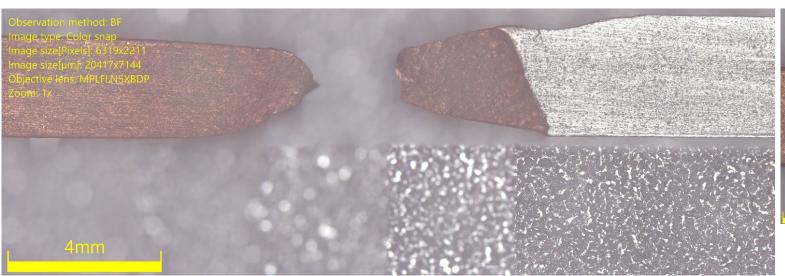








Mechanical testing: Fracture in Cu (weakest spot)







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So what?

- Inconel 625 could be further explored for vacuum flanges.
 - Weakly paramagnetic at 4K. Susceptibility of 1.01- 1.03
- How about using Inconel 625 for structural support as needed?
- EBW of Cu- Inconel 625 is straightforward.

Applications in a CVD (hot chloride) environment need to be evaluated













CVD Nb₃Sn on Cu is possible BUT needs significant developments in the following areas

- Process standardization for Cu cavity preparation.
 - Polishing method, Metric: Surface roughness?
- Nb₃Sn deposition on Cu
 - Process control to obtain a stoichiometric superconductor with desired smoothness.
 - Post processing: No post processing is best...
 - Heat treatment?
 - Thickness control- Address cavity shape
 - Developing Nb₃Sn polishing strategies to remove layers controllably- new electro/ chemical/ mechanical polishing recipes?
- Dealing with soft Cu structures
 - Reinforcements
 - Support structures, flanges etc.











